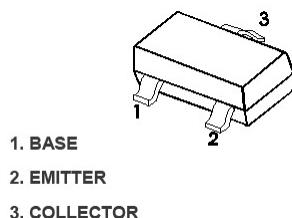




S8550 TRANSISTOR(PNP)

SOT-23 贴片塑封三极管

SOT-23 Plastic-Encapsulate Transistors

SOT-23

Marking: 2TY

特征 Features

- 与 S8050 配对; Complementary to S8050
- 最大功率耗散 300mW; Power Dissipation of 300mW
- 高稳定性和可靠性。High Stability and High Reliability

机械数据 Mechanical Data

- 封装: SOT-23 封装 SOT-23 Small Outline Plastic Package
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性($T_A = 25^\circ\text{C}$ 除非另有规定)Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
Collector-Base Voltage	V_{CBO}	-40	V
Collector-Emitter Voltage	V_{CEO}	-25	V
Emitter -Base Voltage	V_{EBO}	-5	V
Collector Current-Continuous	I_C	-500	mA
Collector Power Dissipation	P_C	300	mW
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55-+150	$^\circ\text{C}$
Thermal resistance From junction to ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$

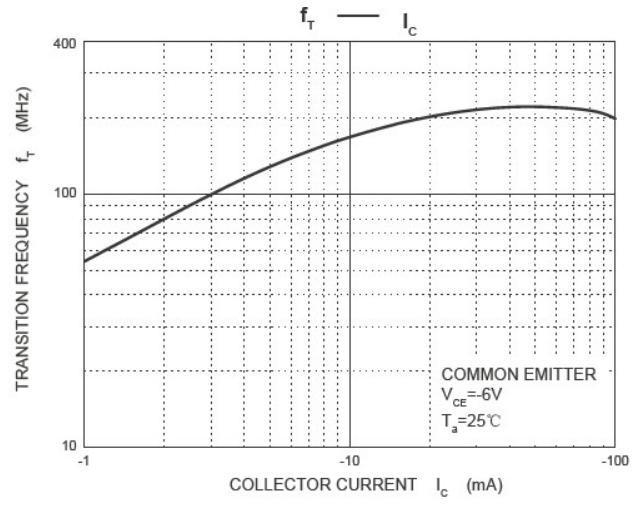
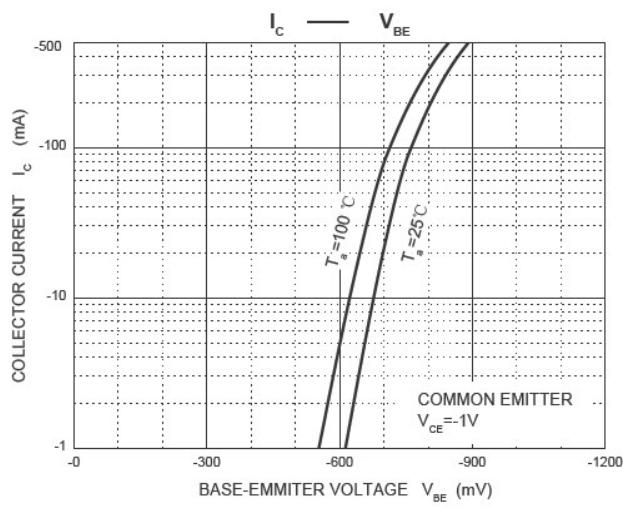
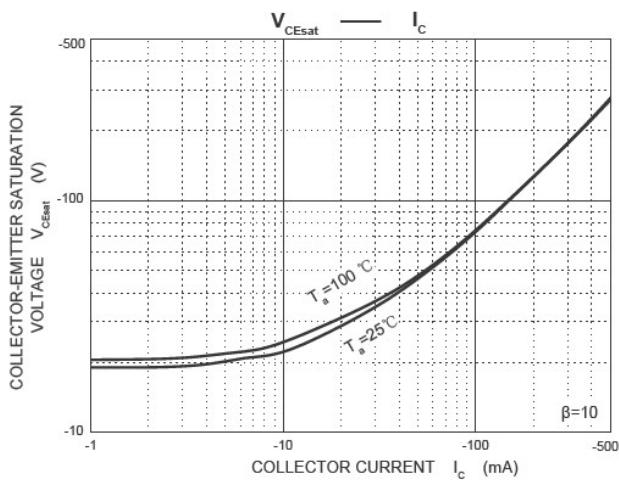
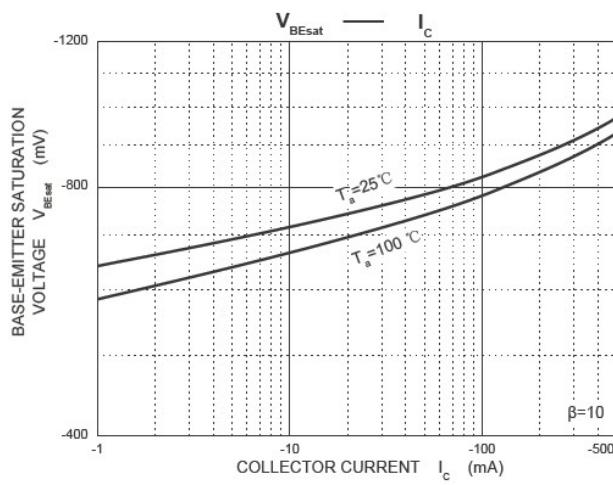
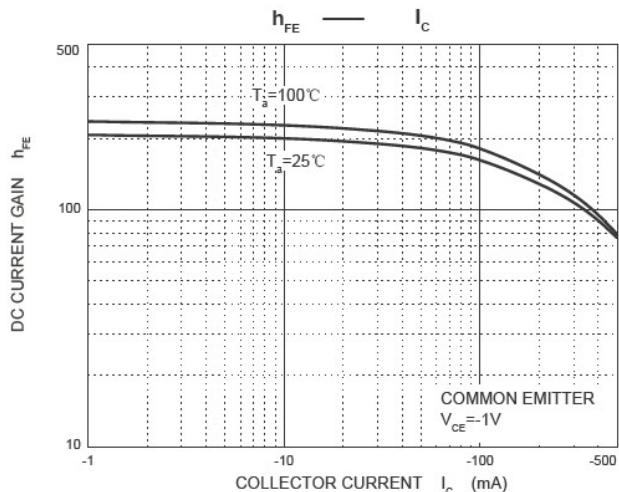
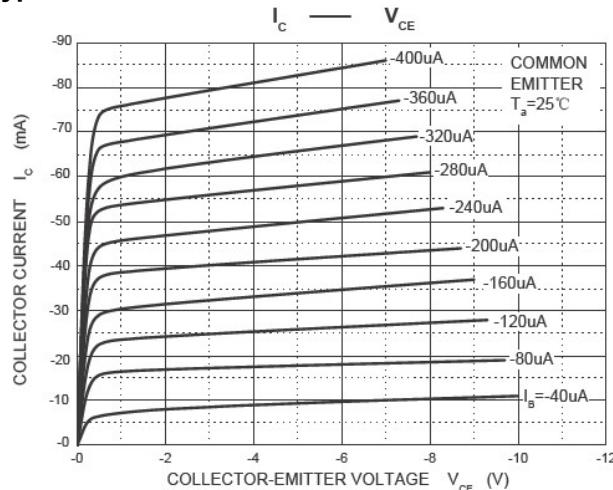
电特性 ($T_A = 25^\circ\text{C}$ 除非另有规定)Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

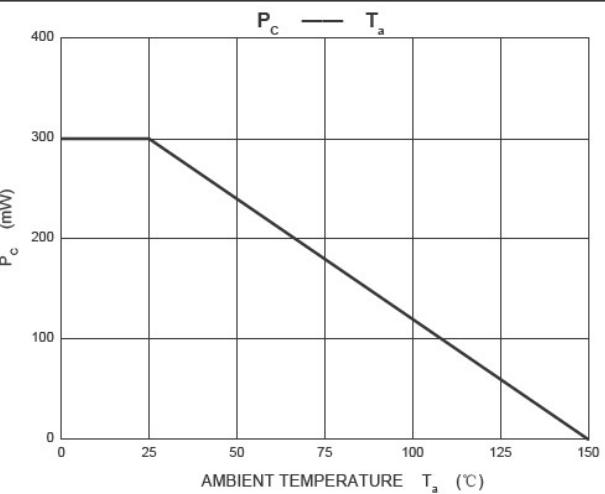
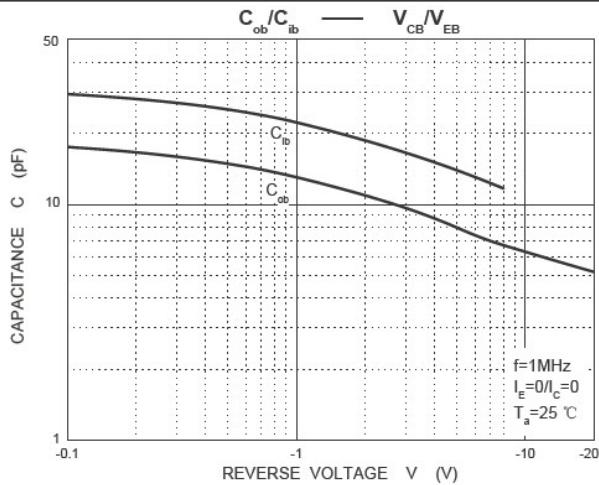
参数 Parameter	符号 Symbols	测试条件 Test Condition	界限 Limits		单位 Unit
			Min	Max	
Collector-base breakdown voltage	$V_{(BR)CBO}$	$I_C=-100\mu\text{A}, I_E=0$	-40		V
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	$I_C=-1\text{mA}, I_B=0$	-25		V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	$I_E=-100\mu\text{A}, I_C=0$	-5		V
Collector cut-off current	I_{CEO}	$V_{CE}=-20\text{V}, I_B=0$		-100	nA
Collector cut-off current	I_{CBO}	$V_{CB}=-40\text{V}, I_E=0$		-100	nA
Emitter cut-off current	I_{EBO}	$V_{EB}=-3\text{V}, I_C=0$		-100	nA
DC current gain	$h_{FE}(1)$	$V_{CE}=-1\text{V}, I_C=-50\text{mA}$	120	400	
	$h_{FE}(2)$	$V_{CE}=-1\text{V}, I_C=-500\text{mA}$	50		
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C=-500\text{mA}, I_B=-50\text{mA}$		-0.60	V
Base -emitter saturation voltage	$V_{BE(sat)}$	$I_C=-500\text{mA}, I_B=-50\text{mA}$		-1.20	V
Transition frequency	f_T	$V_{CE}=-6\text{V}, I_C=-20\text{mA}, f=30\text{MHz}$	150		MHz

CLASSIFICATION OF $h_{FE}(1)$

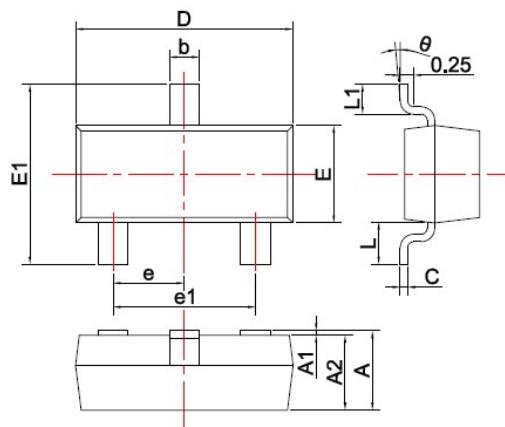
RANK	L	H	J
RANGE	120-200	200-350	300-400

Typical characteristics





SOT-23 PACKAGE OUTLINE Plastic surface mounted package

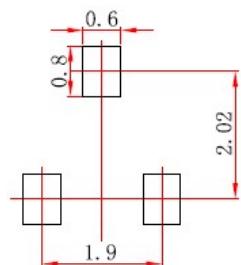


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

Unit: mm

焊盘设计参考 Precautions: PCB Design

Recommended land dimensions for SOT-23 diode. Electrode patterns for PCBs



Note:

1. Controlling dimension: In millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.